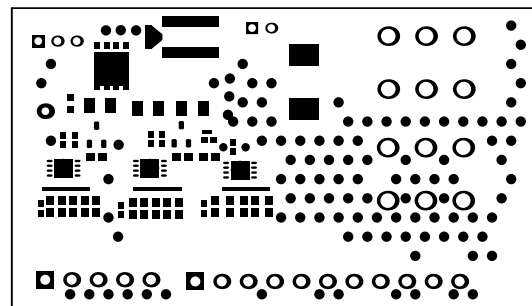
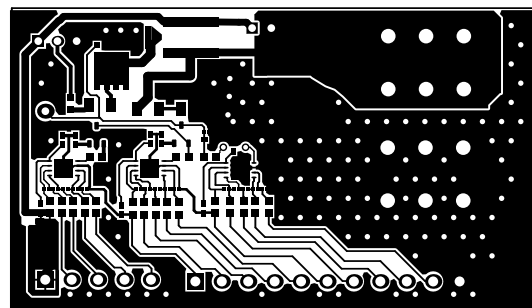


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: bq77180	REV: 1.0	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA00108		
PLOT NAME = Top Overlay	GENERATED : 2/6/2017	11:12:57 AM	TEXAS INSTRUMENTS

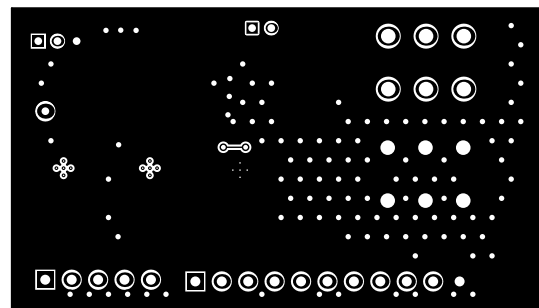


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: bq77180	REV: 1.0	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA00108		
PLOT NAME = Top Solder Mask	GENERATED : 2/6/2017 11:12:58 AM	TEXAS INSTRUMENTS	

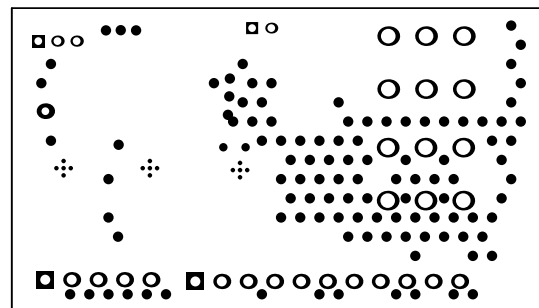
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric1	FR-4	24.51mil	4.8	
5	Bottom Layer	Copper	2.80mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				



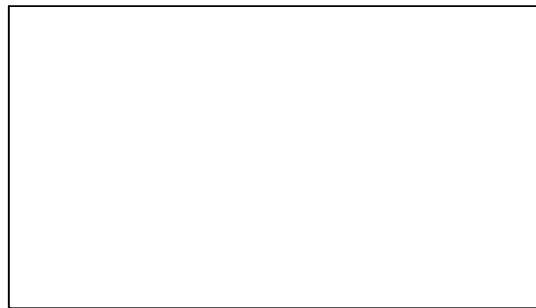
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: bq77180	REV: 1.0	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA00108		
PLOT NAME = Top Layer	GENERATED : 2/6/2017	11:13:00 AM	TEXAS INSTRUMENTS



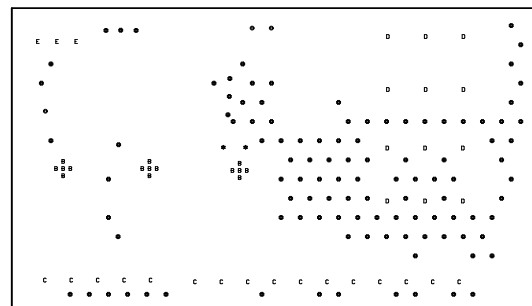
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: bq77180	REV: 1.0	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA00108		
PLOT NAME = Bottom Layer	GENERATED : 2/6/2017 11:13:01 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: bq77180	REV: 1.0	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA00108		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/6/2017 11:13:02 AM	TEXAS INSTRUMENTS	

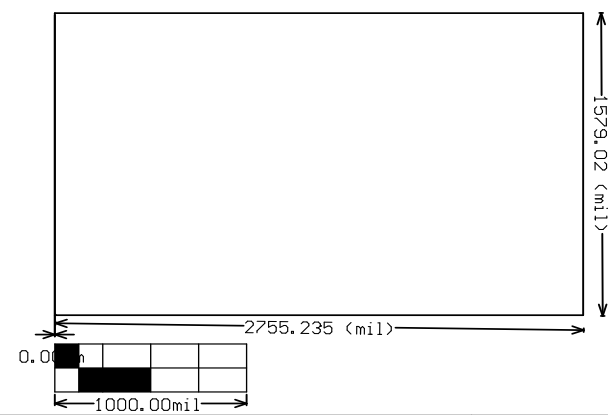


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: bq77180	REV: 1.0	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA00108		
PLOT NAME = Bottom Overlay	GENERATED : 2/6/2017	11:13:03 AM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
B	15	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
*	2	25.00mil (0.635mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	108	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	3	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
E	3	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
C	16	52.00mil (1.321mm)	PTH	Round	Top Layer - Bottom Layer	
D	12	76.00mil (1.930mm)	PTH	Round	Top Layer - Bottom Layer	
	159 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: bq77180	REV: 1.0	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA00108		
PLOT NAME = Drill Drawing	GENERATED : 2/6/2017	11:13:05 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: bq77180	REV: 1.0	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA00108		
PLOT NAME = Board Dimensions	GENERATED : 2/6/2017	11:13:06 AM	TEXAS INSTRUMENTS

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